

ABSTRACT OF THE DISCLOSURE

The present invention is related to a semiconductor pressure sensor device employed for an application of a micro pressure and includes a thin part constituting a diaphragm, a thick part surrounding the thin part, a strain gage element formed on a surface of the diaphragm in a side of the one main surface, for detecting a pressure, a semiconductor sensor substrate having a first concave part formed by the thin part and the thick part, having an opening part in the other main surface, and whose bottom part corresponds to the thin part, and a support member comprising a second concave part and the support member is fixed on the thick part of the semiconductor sensor substrate in a side of the other main surface so that an opening part of the second concave part faces with the opening part of the first concave part and has a positional relationship to be included in the opening part of the first concave part in a plane view.